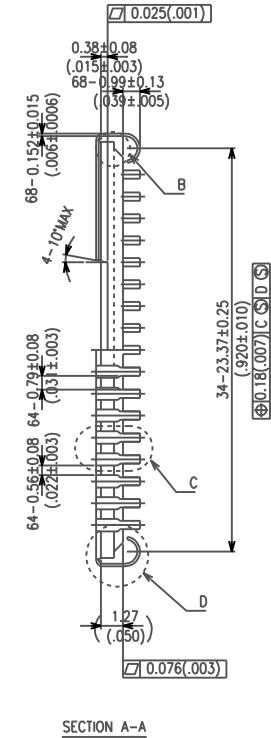
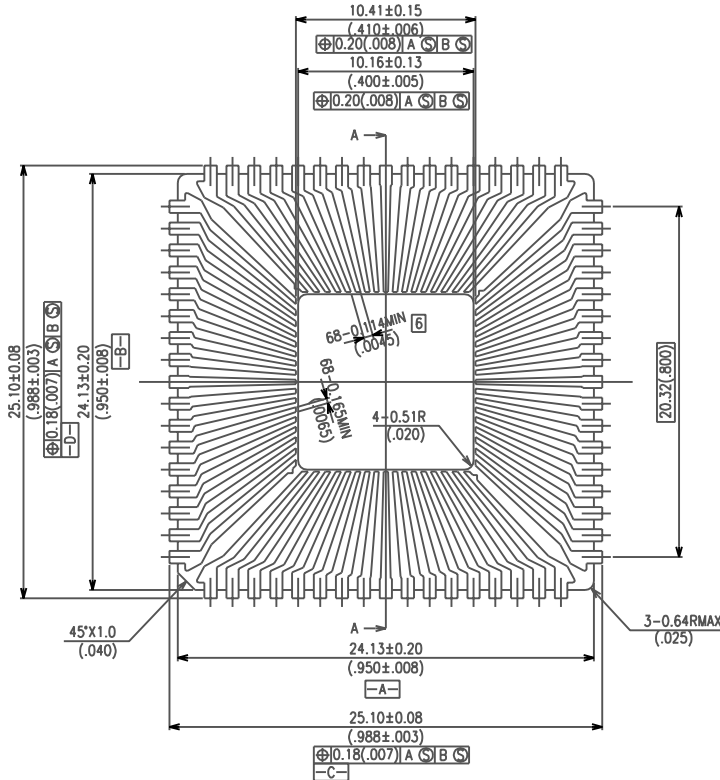
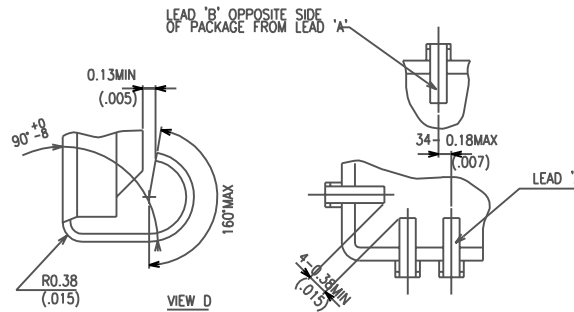
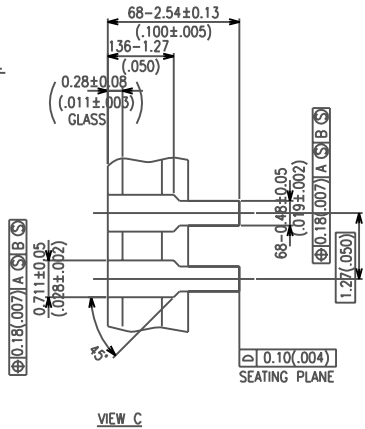
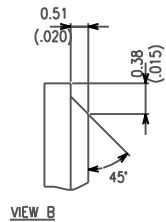
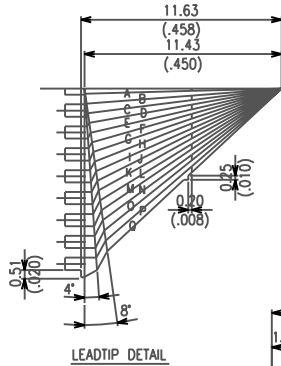


NOTES

1. MATERIALS:
 CERAMIC TO OPAQUE, 90-94% AL₂O₃
 SOLDER GLASS TO BE 7583.
 MAX PULLBACK TO BE 0.25(.010)
 FROM CERAMIC EDGE.
 DIE ATTACH AREA TO BE Au. 120
 MICROINCH MIN.
 LEAD FRAME TO BE ALLOY 42
 TYPE B MIL 38510 PARAGRAPH 3.5.6.1
 WITH ALUMINIUM BOND PADS. 100MICROINCH THICK
 AND 35 MILS IN LENGTH WITH NO
 PULL BACK.
3. THERE WILL BE NO UNSUPPORTED
 BOND PADS GREATER THAN 0.25(.010)
4. ADJACENT BOND PADS MUST BE
 CO-PLANAR WITHIN 0.15(.006).
 TOTAL CO-PLANARITY NO GREATER
 THAN 0.25(.010)
5. THERE WILL BE NO NICKS, CUTS
 OR GLASS IN THE BOND RADIUS
6. MINIMUM INTERNAL METAL SEPARATION, OTHER THAN BOND
 FINGERS, TO BE 0.13(.005)

A	1.45"
B	4.37"
C	7.27"
D	10.13"
E	12.98"
F	15.80"
G	18.57"
H	21.28"
I	23.97"
J	26.57"
K	29.12"
L	31.60"
M	34.03"
N	36.38"
O	38.65"
P	40.87"
Q	43.00"



JEDEC TYPE

MODIFICATIONS	NAME	68LD QUAD CERPAC 'J'(950-400)	TOLERANCES:	DRAWN	CHECKED
	SCALE	5 : 1	UNLESS OTHERWISE SPECIFIED	K.OKADA	
	MATERIAL			APPROVED	DATE
C H A N G E					JUN.15'88
DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION	
				KYOTO JAPAN	DWG No. QC-068271-J-1

